



Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-59. (Canceled)

60. (New) A method of manufacturing a wiring substrate, comprising:

disposing first and second droplets over a substrate, the first and second droplets not being in contact with each other, each of the first and second droplets including a first solvent component and a first functional particle;

irradiating the first and second droplets with a first light to form first and second applied films over the substrate, the first and second applied films not being in contact with each other, each of the first and second applied films including a part of the first solvent component and the first functional particle;

disposing a third droplet between the first and second applied films, the third droplet contacting at least one of the first and second applied films, the third droplet including a second solvent component and a second functional particle;

irradiating the third droplet with the first light to form a third applied film between the first and second applied films, the third applied film contacting at least one of the first and second applied films, the third applied film including a part of the second solvent component and the second functional particle; and

heating the first, second, and third applied films to exclude the part of the first solvent component and the second solvent component to form a functional material.

61. (New) The method of manufacturing a wiring substrate according to claim 60, the process of heating the first, second, and third applied films including irradiating the first, second, and third applied films with a second light, an intensity of the second light being higher than that of the first light.

62. (New) The method of manufacturing a wiring substrate according to claim 60, each of the first and second applied films including a coating film that coats the first functional particle, the coating film being removed at the process of heating the first, second, and third applied films.

63. (New) The method of manufacturing a wiring substrate according to claim 60, the first and second droplets being discharged by a first head of an inkjet apparatus.

64. (New) The method of manufacturing a wiring substrate according to claim 60, the first and second droplets being discharged by a first head of an inkjet apparatus, the third droplet being discharged by a second head of an inkjet apparatus.

65. (New) The method of manufacturing a wiring substrate according to claim 60, the first light being a wide beam that is correspondingly beamed to the first and second droplets.

66. (New) The method of manufacturing a wiring substrate according to claim 60, the first light being beamed to the first and the second droplets through a diffraction optical element.

67. (New) The method of manufacturing a wiring substrate according to claim 60, the first light being reflected by a reflector before the first light is beamed to the first and second droplets.

68. (New) The method of manufacturing a wiring substrate according to claim 60, the substrate being made of a transparent material, the first light passing from a second surface of the substrate to a first surface of the substrate, the first and the second droplets being disposed over the first surface of the substrate.

69. (New) The method of manufacturing a wiring substrate according to claim 60, a viscosity of the first droplet being lower than that of the first applied film.

70. (New) The method for manufacturing a wiring substrate according to claim 60, each of the first and second droplets including a photothermal conversion material that has an absorption band in the wavelength region of the first light.

71. (New) A method of manufacturing a wiring substrate, comprising:

disposing a first droplet over a substrate, the first droplet including a first solvent component and a first functional particle;

irradiating the first droplet with a first light to form a first applied film over the substrate, the first applied film including a part of the first solvent component and the first functional particle;

disposing a second droplet over the substrate, the second droplet contacting at least a part of the first applied film, the second droplet including a second solvent component and a second functional particle;

irradiating the second droplet with the first light to form a second applied film over the substrate, the second applied film contacting at least a part of the first applied film, the second applied film including a part of the second solvent component and the second functional particle;

heating the first and second applied films to exclude the part of the first and second solvent component to form a functional material.

72. (New) The method of manufacturing a wiring substrate according to claim 71, the process of heating the first and second applied films including irradiating the first and second applied films with a second light, an intensity of the second light being higher than that of the first light.